



# TIDA00728 Front Port USB Type-C Extender Test Procedure

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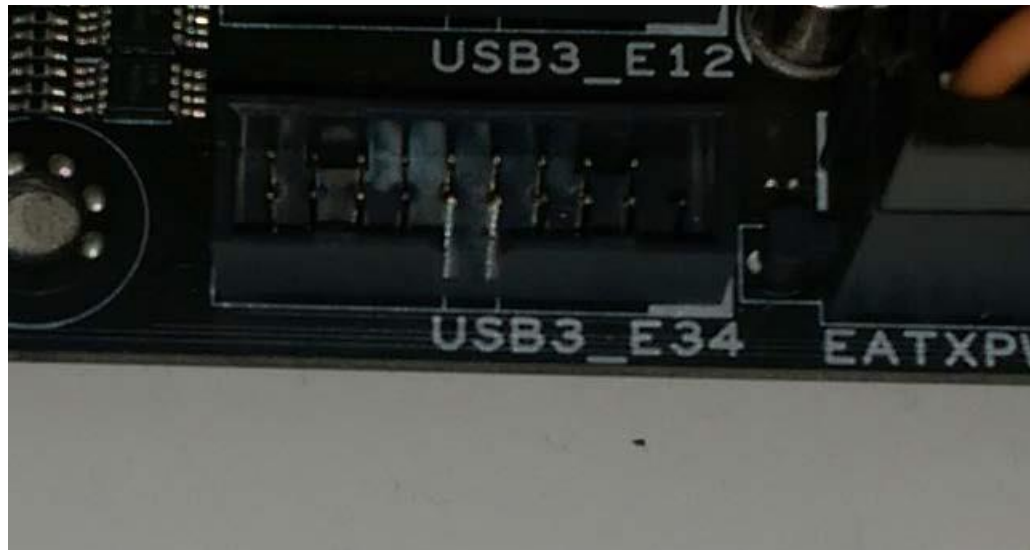
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## Material needed for test:

1. PC with USB3.0 Host with TI xHCI Spy or Intel USB Tree VIEW installed
2. Internal USB 3.0 Motherboard Female to Female Extender Cable
3. USB Type-C Plug to USB3.0 Type-A Receptacle Cable
4. SuperSpeed USB3.0 mass storage device
5. Hi Speed USB2.0 mass storage device

## Test Procedure:

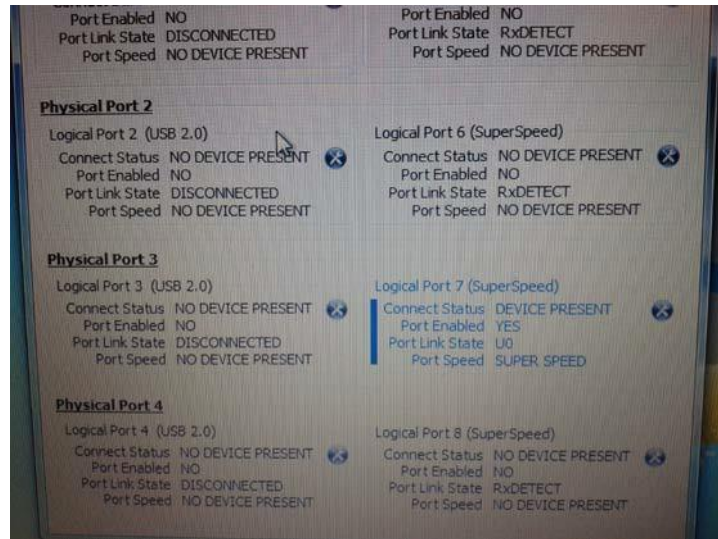
1. Connect TIDA00728 EVM to motherboard USB 3.0 Host internal connector with USB 3.0 Extender Cable



2. Connect USB 3.0 mass storage device to TIDA00728 EVM via Type-C to Type A cable



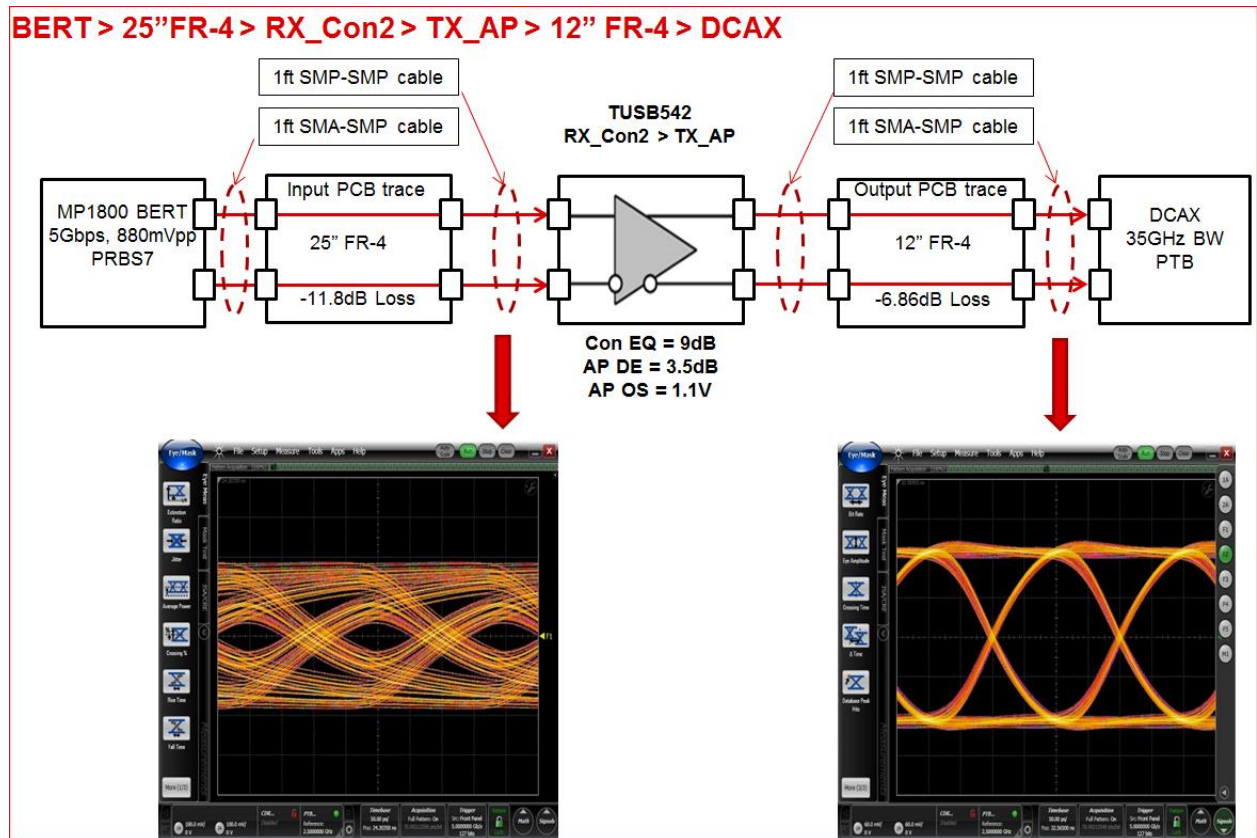
3. Run xHCI Spy tool or USBTreeView on the USB host PC
4. Check if the device is recognized as SuperSpeed device



5. Connected USB2.0 device to TIDA00728 EVM
6. Check if the device is recognized as Hi Speed device

## Capture compliance eye diagram

- Connect a MP 1800 Bert configured at 5Gbps, 880mVpp PRBS7 to the Rx lines of the TUSB542.
- Configure the TUSB542 using Conn EQ = 9dB, AP DE = 3.5dB, AP OS = 1.1V.
- At the Tx lines of the TUSB542 connect a DCAX 35GHz BW PTB



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